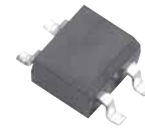


Surface Mount Bridge Rectifiers

PRODUCT SUMMARY

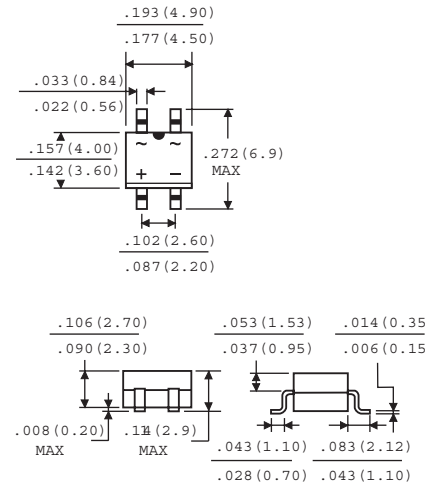
0.8 Amps Miniature Glass Passivated
Fast Recovery Surface Mount Bridge Rectifiers



FEATURES

- Ideal for printed circuit board
- Reliable low cost construction utilizing molded plastic technique
- High surge current capability
- High temperature soldering guaranteed:
260 °C / 10 seconds at 5 lbs., (2.3 kg) tension
- Small size, simple installation
- Pure tin plated terminal, Lead free.
- Leads solderable per MIL-STD-202 Method 208

MBS



 **Pb-free; RoHS-compliant**

Dimensions in inches and (millimeters)

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified.

Single phase, half wave, 60 Hz, resistive or inductive load.

For capacitive load, derate current by 20%

Type Number	Symbol	RMB2S	RMB4S	RMB6S	Units
Maximum Recurrent Peak Reverse Voltage	V_{RRM}	200	400	600	V
Maximum RMS Voltage	V_{RMS}	140	280	420	V
Maximum DC Blocking Voltage	V_{DC}	200	400	600	V
Maximum Average Forward Rectified Current On glass-epoxy P.C.B. On aluminum substrate	$I_{(AV)}$		0.5 0.8		A
Peak Forward Surge Current, 8.3 ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	I_{FSM}		30		A
Maximum Instantaneous Forward Voltage @ 0.4A	V_F		1.0		V
Maximum DC Reverse Current @ $T_A=25^\circ\text{C}$ at Rated DC Blocking Voltage @ $T_A=125^\circ\text{C}$	I_R		5.0 100		μA μA
Maximum Reverse Recovery Time at (Note 1)	T_{rr}		150		nS
Typical Junction Capacitance Per Leg	C_j		13		pF
Typical Thermal Resistance Per Leg	$R_{\theta JA}$		85		$^\circ\text{C}/\text{W}$
Operating Temperature Range	T_J		-55 to +150		$^\circ\text{C}$
Storage Temperature Range	T_{STG}		-55 to +150		$^\circ\text{C}$

Note: Reverse Recovery Test Conditions: $I_F=0.5\text{A}$, $I_R=1.0\text{A}$, $I_{RR}=0.25\text{A}$

RATINGS AND CHARACTERISTIC CURVES (RMB2S THRU RMB6S)

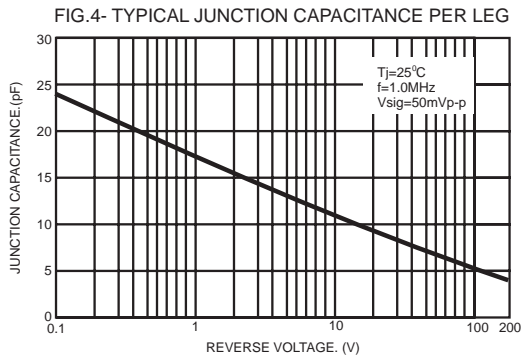
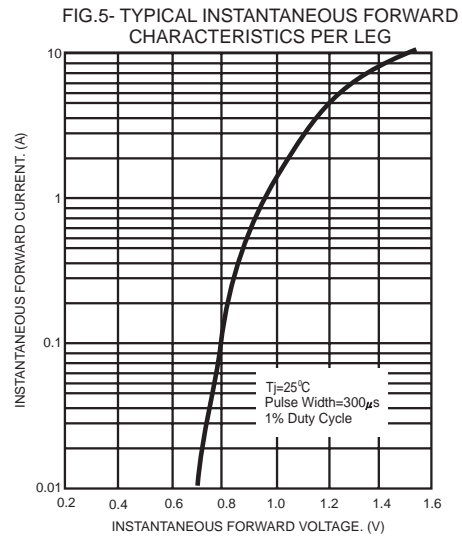
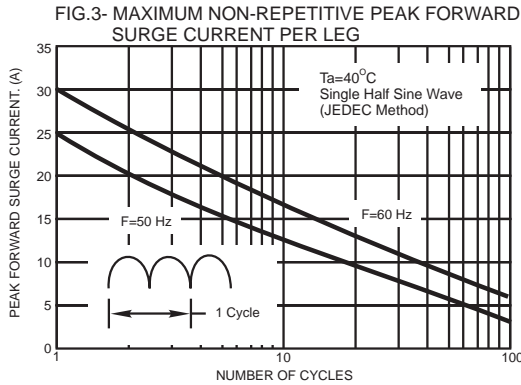
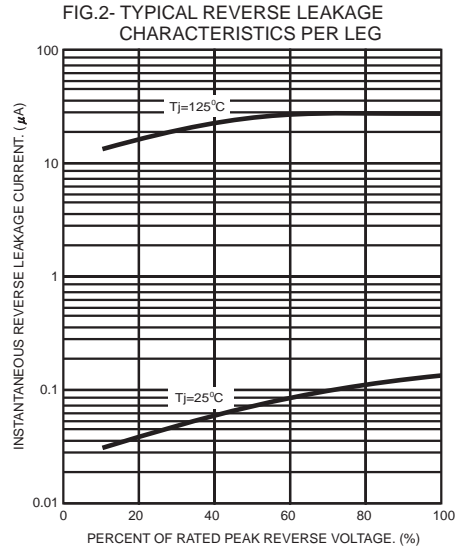
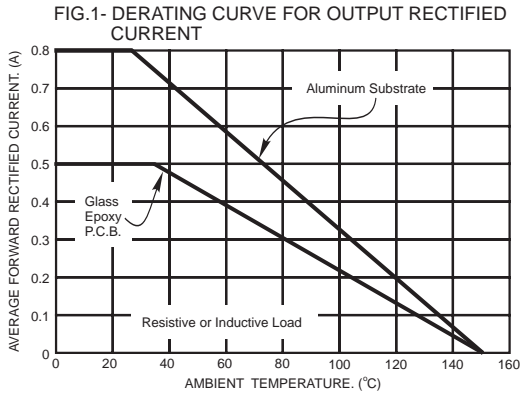
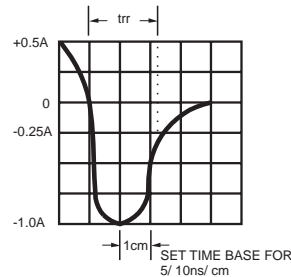
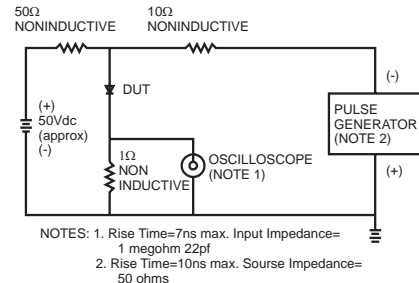


FIG.6- REVERSE RECOVERY TIME CHARACTERISTIC AND TEST CIRCUIT DIAGRAM



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